

3N65

Power MOSFET

3A, 650V N-CHANNEL
POWER MOSFET

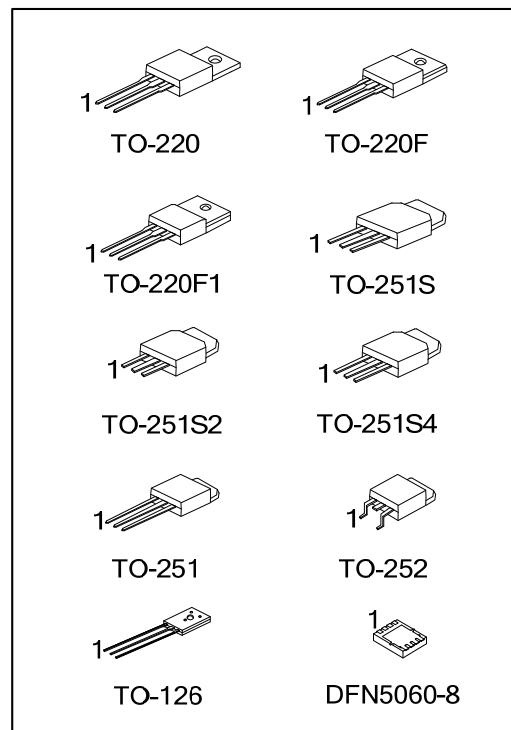
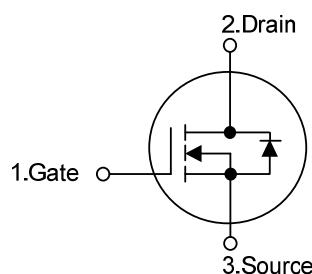
■ DESCRIPTION

The **3N65** is a high voltage and high current power MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and high rugged avalanche characteristics. This power MOSFET is usually used in high speed switching applications at power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

■ FEATURES

- * $R_{DS(ON)} < 3.8\Omega$ @ $V_{GS} = 10V$, $I_D = 1.5A$
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability, high ruggedness

■ SYMBOL



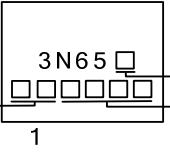
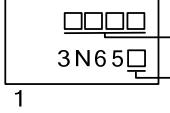
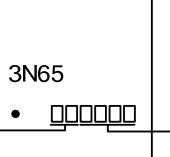
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment								Packing
Lead Free	Halogen Free		1	2	3	4	5	6	7	8	
3N65L-TA3-T	3N65G-TA3-T	TO-220	G	D	S	-	-	-	-	-	Tube
3N65L-TF1-T	3N65G-TF1-T	TO-220F1	G	D	S	-	-	-	-	-	Tube
3N65L-TF3-T	3N65G-TF3-T	TO-220F	G	D	S	-	-	-	-	-	Tube
3N65L-TM3-T	3N65G-TM3-T	TO-251	G	D	S	-	-	-	-	-	Tube
3N65L-TMS-T	3N65G-TMS-T	TO-251S	G	D	S	-	-	-	-	-	Tube
3N65L-TMS2-T	3N65G-TMS2-T	TO-251S2	G	D	S	-	-	-	-	-	Tube
3N65L-TMS4-T	3N65G-TMS4-T	TO-251S4	G	D	S	-	-	-	-	-	Tube
3N65L-TN3-R	3N65G-TN3-R	TO-252	G	D	S	-	-	-	-	-	Tape Reel
3N65L-T60-K	3N65G-T60-K	TO-126	G	D	S	-	-	-	-	-	Bulk
3N65L-K08-5060-R	3N65G-K08-5060-R	DFN5060-8	S	S	S	G	D	D	D	D	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

 (1)Packing Type (2)Package Type (3)Green Package	(1) R: Tape Reel, T: Tube, K: Bulk
	(2) TA3: TO-220, TF1: TO-220F1, TF3: TO-220F, TM3: TO-251, TN3: TO-252, TMS: TO-251S T60: TO-126, K08-5060: DFN5060-8
	(3) G: Halogen Free and Lead Free, L: Lead Free

■ MARKING

Package		MARKING
TO-220 TO-220F TO-220F1 TO-251	TO-251S TO-251S2 TO-251S4 TO-252	 <p>3N65</p> <p>Lot Code ← Data Code →</p> <p>L: Lead Free G: Halogen Free</p> <p>1</p>
	TO-126	 <p>3N65</p> <p>Data Code →</p> <p>Lot Code ← L: Lead Free G: Halogen Free</p> <p>1</p>
	DFN5060-8	 <p>3N65</p> <p>• Date Code →</p> <p>Lot Code ←</p>

■ ABSOLUTE MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	V_{DSS}	650	V
Gate-Source Voltage	V_{GSS}	± 30	V
Avalanche Current (Note 2)	I_{AR}	3.0	A
Continuous Drain Current	I_D	3.0	A
Pulsed Drain Current (Note 2)	I_{DM}	12	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	200 mJ
	Repetitive (Note 2)	E_{AR}	7.5 mJ
Peak Diode Recovery dv/dt (Note 4)	dv/dt	4.5 V/ns	
Power Dissipation	TO-220	P_D	75
	TO-220F/TO-220F1		34
	TO-251/TO-252/TO-251S		50
	TO-251S2/TO-251S4		
	TO-126		17
	DFN5060-8		25
Junction Temperature	T_J	+150	°C
Operating Temperature	T_{OPR}	-55 ~ +150	°C
Storage Temperature	T_{STG}	-55 ~ +150	°C

Note: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature

3. L = 64mH, $I_{AS} = 2.4\text{ A}$, $V_{DD} = 50\text{ V}$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 3.0\text{ A}$, $di/dt \leq 200\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

■ THERMAL DATA

PARAMETER	SYMBOL	RATING	UNIT
Junction to Ambient	θ_{JA}	62.5	°C/W
		110	
		132	
		75 (Note)	
Junction to Case	θ_{JC}	1.67	°C/W
		3.68	
		2.5	
		7.36	
		5 (Note)	

Note: The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

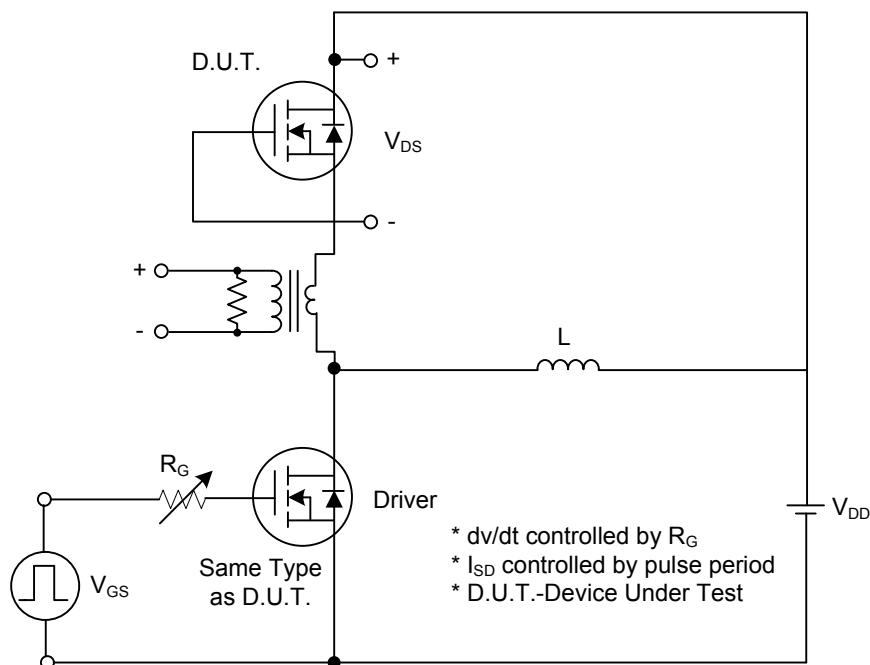
■ ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0 \text{ V}, I_{\text{D}} = 250 \mu\text{A}$	650			V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}} = 650 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		10		μA
Gate-Source Leakage Current	Forward	$V_{\text{GS}} = 30 \text{ V}, V_{\text{DS}} = 0 \text{ V}$		100		nA
	Reverse	$V_{\text{GS}} = -30 \text{ V}, V_{\text{DS}} = 0 \text{ V}$		-100		nA
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$I_{\text{D}} = 250 \mu\text{A}$, Referenced to 25°C		0.6		$\text{V}/^\circ\text{C}$
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{\text{GS(TH)}}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250 \mu\text{A}$	2.0		4.0	V
Static Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}} = 10 \text{ V}, I_{\text{D}} = 1.5 \text{ A}$		2.8	3.8	Ω
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{ISS}	$V_{\text{DS}} = 25 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 1 \text{ MHz}$		430	500	pF
Output Capacitance	C_{OSS}			50	65	pF
Reverse Transfer Capacitance	C_{RSS}			11	20	pF
SWITCHING CHARACTERISTICS						
Total Gate Charge	Q_G	$V_{\text{DS}} = 50 \text{ V}, I_{\text{D}} = 1.3 \text{ A}, V_{\text{GS}} = 10 \text{ V}$ (Note 1, 2)		51	70	nC
Gate-Source Charge	Q_{GS}			13		nC
Gate-Drain Charge	Q_{GD}			11		nC
Turn-On Delay Time	$t_{\text{D(ON)}}$	$V_{\text{DD}} = 30 \text{ V}, I_{\text{D}} = 0.5 \text{ A}, R_G = 25 \Omega$ (Note 1, 2)		32	45	ns
Turn-On Rise Time	t_R			64	80	ns
Turn-Off Delay Time	$t_{\text{D(OFF)}}$			115	140	ns
Turn-Off Fall Time	t_F			60	75	ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Maximum Continuous Drain-Source Diode Forward Current	I_S				3.0	A
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}				12	A
Drain-Source Diode Forward Voltage	V_{SD}	$V_{\text{GS}} = 0 \text{ V}, I_S = 3.0 \text{ A}$			1.4	V

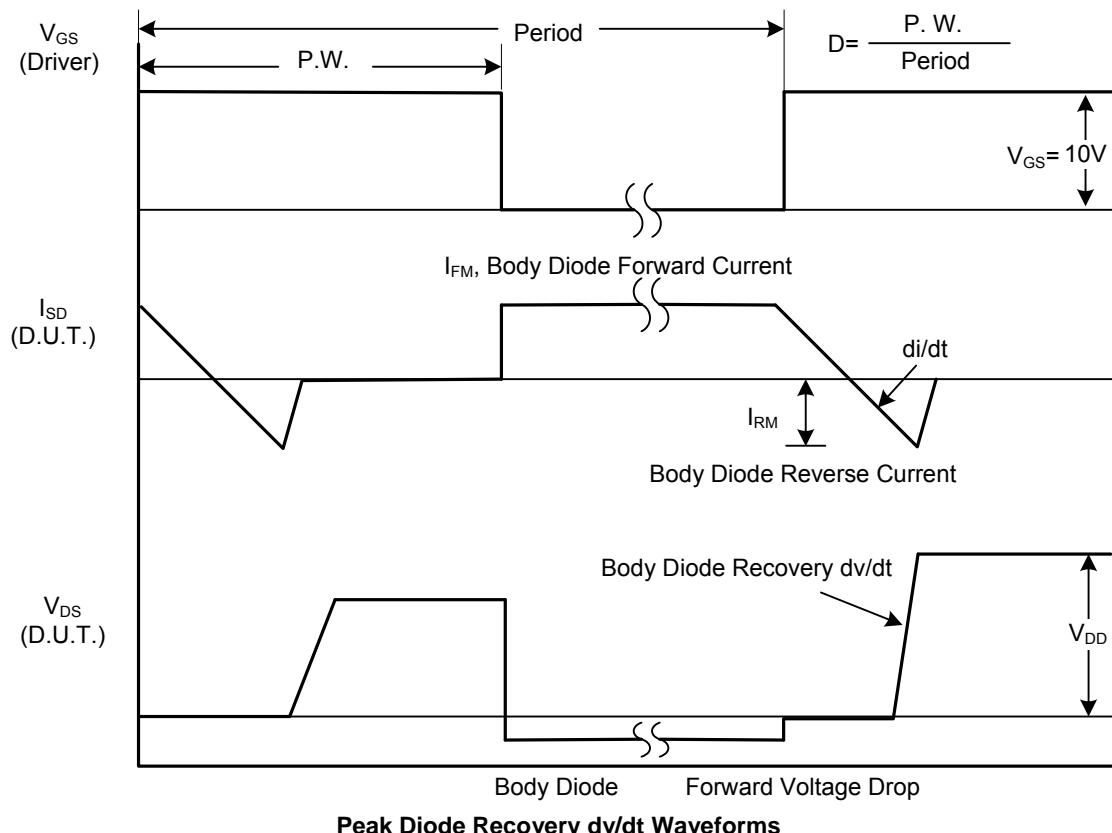
Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. L = 64mH, $I_{\text{AS}} = 2.4 \text{ A}$, $V_{\text{DD}} = 50 \text{ V}$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$

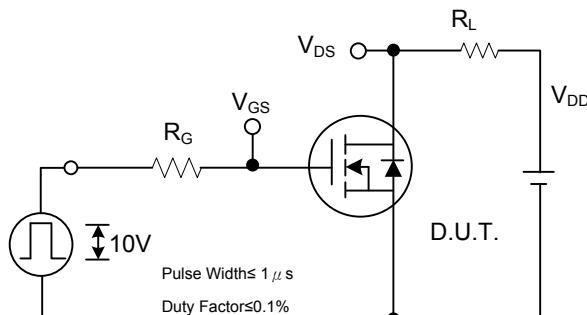
■ TEST CIRCUITS AND WAVEFORMS



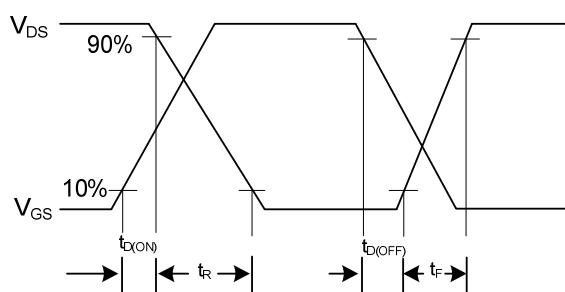
Peak Diode Recovery dv/dt Test Circuit



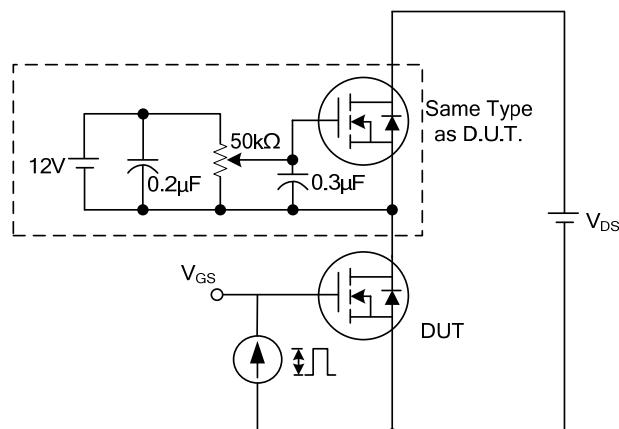
■ TEST CIRCUITS AND WAVEFORMS (Cont.)



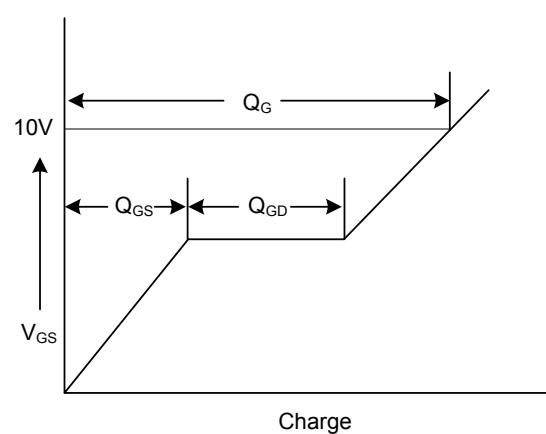
Switching Test Circuit



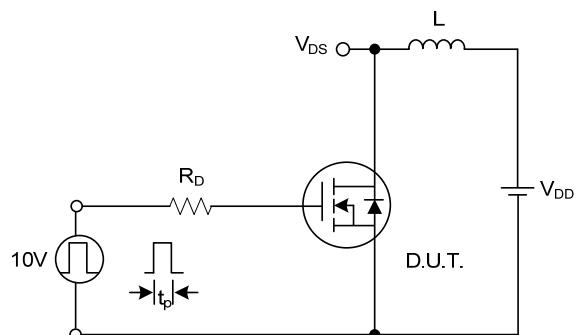
Switching Waveforms



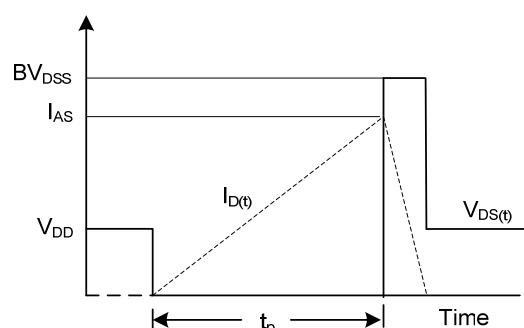
Gate Charge Test Circuit



Gate Charge Waveform



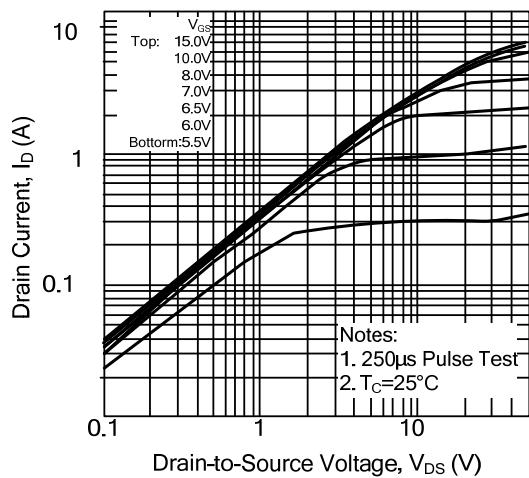
Unclamped Inductive Switching Test Circuit



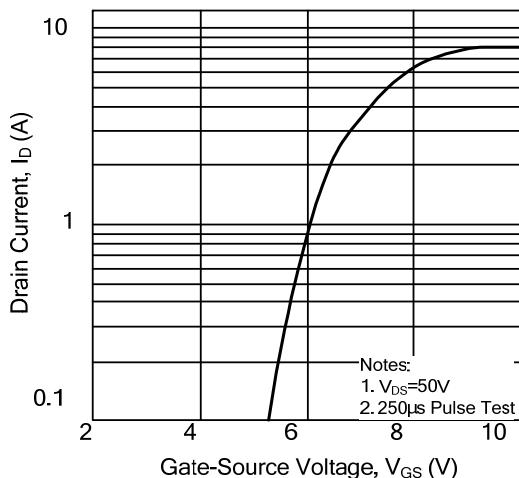
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

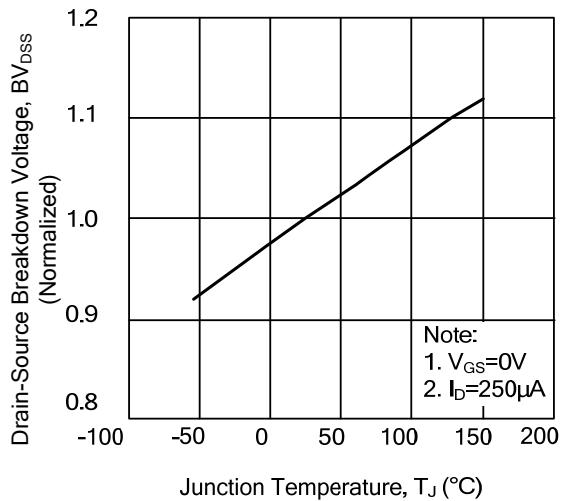
On-State Characteristics



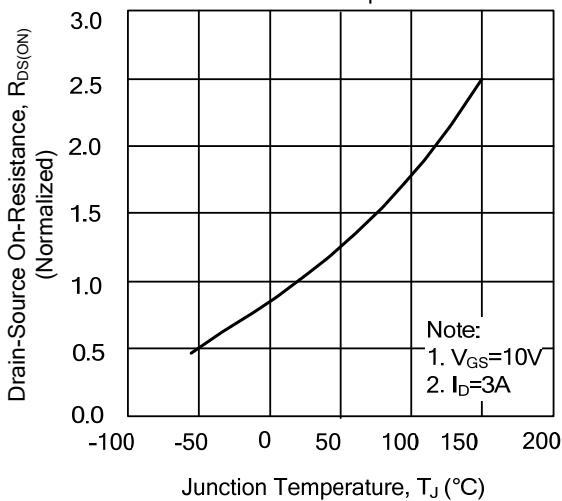
Transfer Characteristics



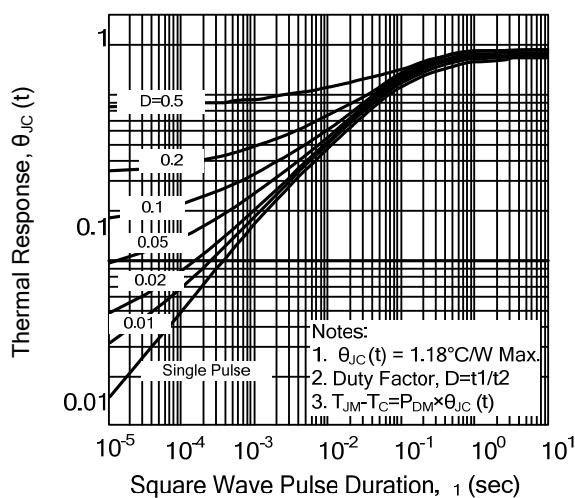
Breakdown Voltage Variation vs. Junction Temperature



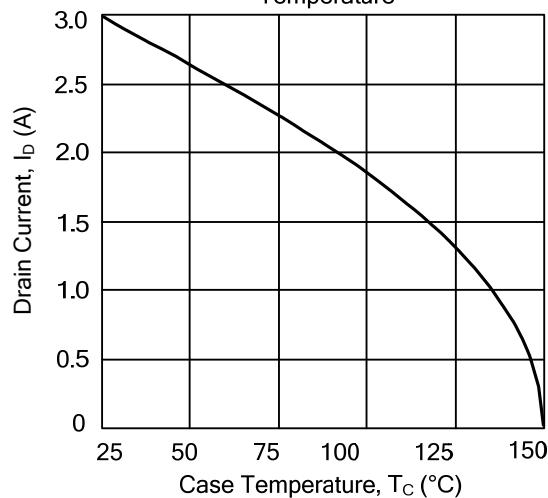
On-Resistance Variation vs. Junction Temperature



Transient Thermal Response Curve



Maximum Drain Current vs. Case Temperature



■ TYPICAL CHARACTERISTICS(Cont.)

